

PART INFORMATION

Mfg Item Number	MKW21D256VHA5R
Mfg Item Name	MAPLGA 63 8*8*0.91 P0.5

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2018-04-14
Response Document ID	00B7K00165D052A1.15
Contact Name	Freescale Semiconductor Inc
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DECLARATION

EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	
EU RoHS Exemption(s)	

MANUFACTURING

Mfg Item Number	MKW21D256VHA5R
Mfg Item Name	MAPLGA 63 8*8*0.91 P0.5
Version	ALL
Weight	0.188200
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Non-Conductive Epoxy/Adhesive	0.0027						g				
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.0002025	g	75000	7.5	1075	0.1075
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Crosslinked acrylate polymer	25767-43-5		0.00054	g	200000	20	2869	0.2869
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Other polymers	-		0.0002025	g	75000	7.5	1075	0.1075
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other polymers	-		0.00054	g	200000	20	2869	0.2869
Non-Conductive Epoxy/Adhesive		Glass	Silica, vitreous	60676-86-0		0.001215	g	450000	45	6455	0.6455
Die Encapsulant, Halogen-free	0.126						g				
Die Encapsulant, Halogen-free		Metals	Other aluminum compounds	-		0.00378	g	30000	3	20085	2.0085
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00126	g	10000	1	6695	0.6695
Die Encapsulant, Halogen-free		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.00378	g	30000	3	20085	2.0085
Die Encapsulant, Halogen-free		Plastics/polymers	Other phenolic resins	-		0.00378	g	30000	3	20085	2.0085
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		0.1071	g	850000	85	569087	56.9087
Die Encapsulant, Halogen-free		Plastics/polymers	Other Non-halogenated Epoxy resins	-		0.0063	g	50000	5	33475	3.3475
Silicon Semiconductor Die	0.012						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.00024	g	20000	2	1275	0.1275
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.01176	g	980000	98	62486	6.2486
Organic Substrate	0.0353						g				
Organic Substrate		Metals	Barium sulfate	7727-43-7		0.00257535	g	72956	7.2956	13684	1.3684
Organic Substrate		Metals	Copper, metal	7440-50-8		0.01060956	g	300554	30.0554	56373	5.6373
Organic Substrate		Plastics/polymers	Epikote 862	28064-14-4		0.0022497	g	63731	6.3731	11953	1.1953
Organic Substrate		Plastics/polymers	Formaldehyde, polymer with 2-methylphenol, glycidyl ether	64425-89-4		0.00398992	g	113029	11.3029	21200	2.12
Organic Substrate		Metals	Gold, metal	7440-57-5		0.00026997	g	7648	0.7648	1434	0.1434
Organic Substrate		Nickel (external applications only)	Nickel	7440-02-0		0.00210868	g	59736	5.9736	11204	1.1204
Organic Substrate		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.00122848	g	34801	3.4801	6527	0.6527
Organic Substrate		Glass	Fibrous-glass-wool	65997-17-3		0.00752444	g	213157	21.3157	39981	3.9981
Organic Substrate		Glass	Silicon dioxide	7631-86-9		0.00064497	g	18271	1.8271	3427	0.3427
Organic Substrate		Solvents, additives, and other materials	Other Aromatic carbonyl compounds	-		0.00041347	g	11713	1.1713	2196	0.2196
Organic Substrate		Metals	Aluminum Hydroxide	21645-51-2		0.00368546	g	104404	10.4404	19582	1.9582
Bonding Wire, P/Cu	0.0002						g				
Bonding Wire, P/Cu		Metals	Copper, metal	7440-50-8		0.0001962	g	981000	98.1	1042	0.1042
Bonding Wire, P/Cu		Metals	Gold, metal	7440-57-5		0.0000002	g	1000	0.1	1	0.0001
Bonding Wire, P/Cu		Metals	Palladium, metal	7440-05-3		0.0000036	g	18000	1.8	19	0.0019
Silicon Semiconductor Die	0.012						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.00024	g	20000	2	1275	0.1275
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.01176	g	980000	98	62486	6.2486

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MKW21D256VHA5R_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MKW21D256VHA5R_IPC1752A.xml